SCBS208A - FEBRUARY 1991 - REVISED JULY 1994

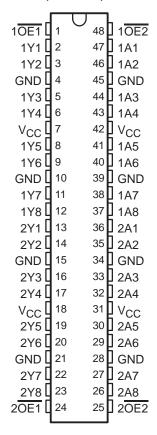
- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

These 16-bit buffers and bus drivers provide a high-performance bus interface for wide data paths.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all corresponding outputs are in the high-impedance state.

SN54ABT16540 . . . WD PACKAGE SN74ABT16540 . . . DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT16540 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16540 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16540 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each 8-bit section)

	INPUTS	OUTPUT				
OE1	OE2	Α	Y			
L	L	L	Н			
L	L	Н	L			
Н	X	Χ	Z			
Х	Н	Χ	Z			

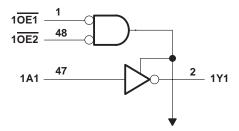
Widebus and EPIC-IIB are trademarks of Texas Instruments Incorporated.

logic symbol[†]

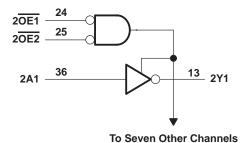
2A8

10E1 48 EN1 10E2 24 & 20E1 EN₂ 25 20E2 47 2 1Y1 1A1 1 ▽ 46 3 1Y2 1A2 5 44 1Y3 1A3 43 6 1A4 1Y4 41 8 1A5 1Y5 9 40 1A6 1Y6 38 11 1Y7 **1A7** 12 37 1A8 1Y8 36 13 1 2♡ 2Y1 2A1 35 14 2Y2 2A2 16 33 2A3 2Y3 32 17 2A4 2Y4 30 19 2A5 2Y5 29 20 2Y6 2A6 27 22 2A7 2Y7 26 23

logic diagram (positive logic)



To Seven Other Channels



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

2Y8

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V _O	. −0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16540	96 mA
SN74ABT16540	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2): DGG package	0.85 W
DL package	1.2 W
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

^{2.} The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions (see Note 3)

					SN74AE	LINUT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	CC Supply voltage				4.5	5.5	V
V _{IH} High-level input voltage				T.	2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage				0	Vcc	V
ІОН	OH High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	A	10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54A	BT16540	SN74ABT16540		UNIT	
				MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNII	
٧ıK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\/-··		V _C C = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3		٧	
VOH		V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2					
		vCC = 4.5 v	$I_{OH} = -32 \text{ mA}$	2*					2			
\/-·		V 45V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
Ц		V _{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±1		±1		±1	μΑ	
lozh		$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			50		50		50	μΑ	
lozL		$V_{CC} = 5.5 \text{ V},$	V _O = 0.5 V			-50		50		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100		Q		±100	μΑ	
ICEX	Outputs high	V _{CC} = 5.5 V,	V _O = 5.5 V			50	Ó	50		50	μΑ	
IO [‡]		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
	Outputs high		I _O = 0,			2	Q.	2		2		
Icc	Outputs low					32		32		32	m _A	
licc	Outputs disabled	V _I = V _{CC} or GND				2	2			2	IIIA	
	Data inputs	One	V _{CC} = 5.5 V, One input at	Outputs enabled			1		1		1	
ΔICC§			Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	$V_{CC} = 5.5 \text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5		
Ci		V _I = 2.5 V or 0.5 V			7						pF	
Co		V _O = 2.5 V or 0.5 V			7						pF	

 $[\]sp{\star}$ On products compliant to MIL-STD-883, Class B, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

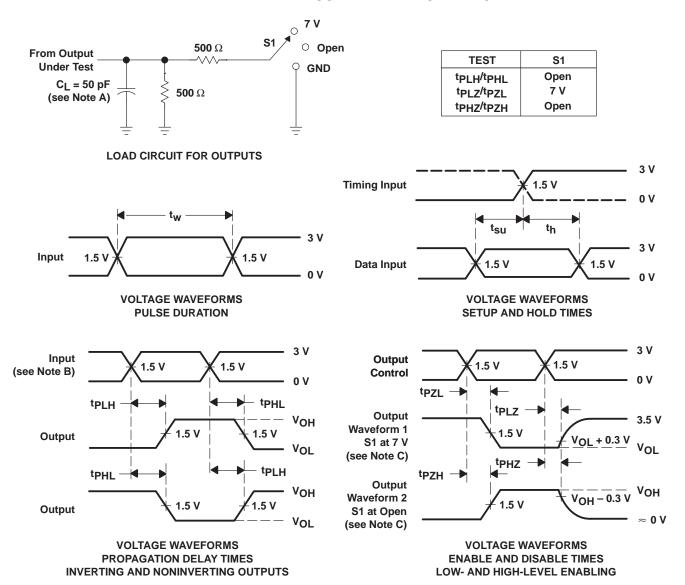
SN54ABT16540, SN74ABT16540 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS208A - FEBRUARY 1991 - REVISED JULY 1994

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT16540		SN74ABT16540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
tPLH	А	Y	1	2.3	3.3	1	4.2	1	4.1	ns
t _{PHL}			1.1	2.5	4.1	1.1	4.4	1.1	4.3	
^t PZH	ŌĒ	Y	1.1	3.1	4.2	1.15	5.2	1.1	5.1	ns ns
tpZL			1.6	3.7	4.8	1.6	6	1.6	5.9	
t _{PHZ}	ŌĒ	OE Y	1.6	3.4	4.6	1.6	5.4	1.6	5.3	
tPLZ			1.4	2.9	4.1	1.4	4.7	1.4	4.4	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated